PARYLENE **COATING PROCESS**

- Thin Film
- Pinhole Free
- Electrically Insulating
- Reduced Friction
- Chemical and Solvent Resistance
- Medical Applications

Typical Industries

- Military Electronics (Qualified to MIL-I-46058C)
- Marine and Related Environments
- Medical Device Applications
- Rubber Seals, Gaskets, Tubing and O-rings
- **Commercial Electronics**

Compatibility & Performance

- Hydrophobic
- Compatible with Elastomers
- Low Outgassing Properties
- **High Dielectric Strength**
- USP Class VI Biocompatibility

PROPERTIES

High reliability - Suitable for both military and commercial applications Particle retention - Upgrades electronic and mechanical devices True conformality - Uniform thickness on all surfaces Out gassing - Virtually none Light weight - compared to other coatings Solvent resistance - Insoluble in common solvents Wide temperature range - From -220 C to +150 C

Outstanding barrier - Very low permeability to moisture and gases



Stress-free coatings - Sensitive circuitry unchanged by coating Acid and base resistance - Resists attack from exposure Radiation resistance - Suitable for space applications Fungus and bacteria resistance - Excellent Low coefficient of friction - Outstanding lubricity Electrical breakdown - Extremely high dielectric strength Transparency - thin films are of optical clarity Mechanical - High tensile and yield strength

UNITED STATES:

E/M Chicago E/M Detroit MIC Fremont, IN E/M Hartford E/M Minneapolis E/M Los Angeles (No. Hollywood) (Chatsworth)

MIC Philadelphia 630-620-6808 PCS Katy, TX 586-566-6800 260-495-4445

860-224-9148

651-780-3202

818-983-1952

818-407-6280

CANADA: MIC Ingersoll

CHINA MIC Suzhou 281-391-7765 519-485-5500

215-638-0888

GERMANY: MIC Unna

FACILITY LOCATIONS:

49-2303-91880

UNITED KINGDOM: MIC Evesham

44-1386-421444





IRFI AND. 86-158-6241-7890 MIC Evesham

353-91-780-300

TECHNICAL SPECIFICATIONS

TYPICAL FILM PROPERTIES	Parylene N	Parylene C	Parylene D
Physical & Mechanical Properties Tensile strength, psi Tensile strength, Mpa Yield strength, Mpa Tensile modulus, Mpa Elongation to break, % Density, g/cm2 Coefficient of friction static dynamic Water absorption, % (24 hr) Index of refraction, Nd23	6,500 45 6,300 43 2,400 40 1,110 0.25 0.25 0.01 (0.019") 1.661	10,000 69 8,000 55 3,200 200 1,289 0.29 0.29 0.06 (0.029") 1.639	11,000 76 9,000 62 2800 10 1,418 0.33 0.31 NA 1.669
Typical Electrical Properties			
Dielectric strength, (Volts/mil at 1 mil) Volume resistivity, 23 C, 50% RH (Ohm-cm) Surface resistivity, 23 C, 50% RH (Ohms) Dielectric constant: 60 Hz 1,000 Hz 1,000,000 Hz Dissipation factor: 60 Hz 1,000 Hz 1,000,000 Hz	7,000 1 x 10 to the 17th 10 to the 15th 2.65 2.65 2.65 0.0002 0.0002 0.0006	6,800 6 x 10 to the 16th 10 to the 15th 3.15 3.1 2.95 0.02 p.p.19 0.013	5,500 2 x 10 to the 16th 10 to the 16th 2.84 2.82 2.8 0.004 0.003 0.002
Typical Barrier Properties			
GAS PERMEABILITY Nitrogen Oxygen Carbon dioxide Hydrogen sulfide Sulphur dioxide Chlorine MOISTURE VAPOR TRANSMISSION	7.7 30 214 795 1.89 74 1.5	0.95 7.1 7.7 13 11 0.35 0.14	4.5 32 13 1.45 4.75 0.55 0.25
TYPICAL THERMAL PROPERTIES			
Melting temperature (degrees C) Linear coefficient of expansion, (10 to the -5th/C) Thermal conductivity, (10 to the -4th (cal/sec)/(cm squared C/ C)	410 6.9 3	290 3.5 2	380 NA NA